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#### What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

#### Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

#### Details

Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	25MHz
Connectivity	SMBus (2-Wire/I <sup>2</sup> C), SPI, UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	25
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1.25K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VFQFN Exposed Pad
Supplier Device Package	28-QFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/c8051f315

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

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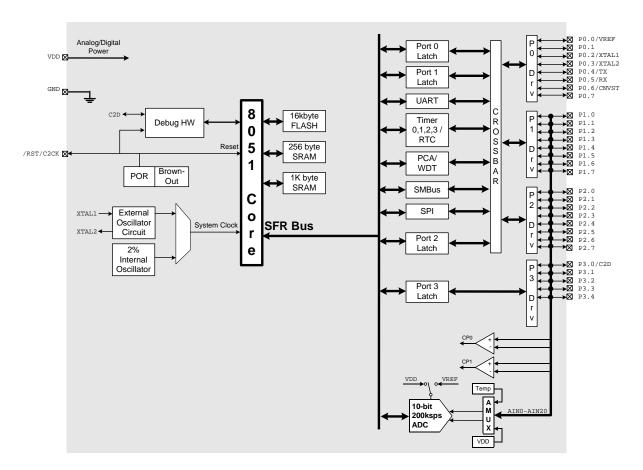


Figure 1.1. C8051F310 Block Diagram



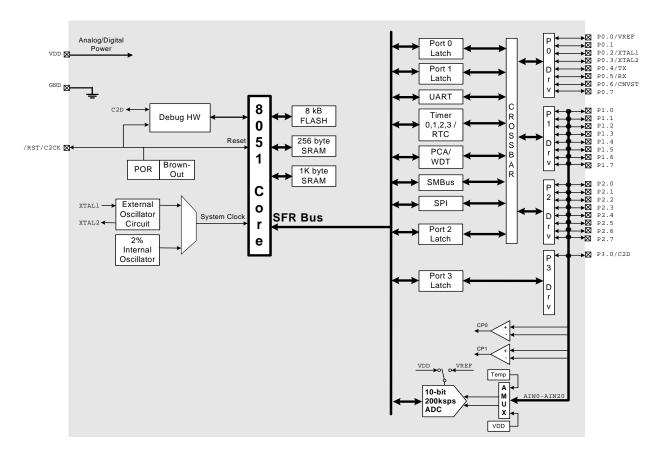


Figure 1.4. C8051F313 Block Diagram



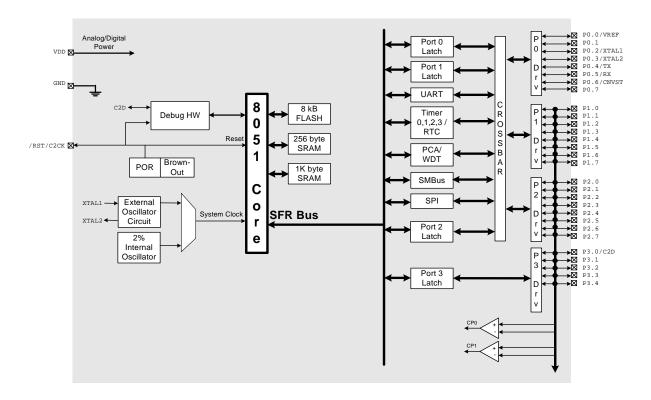


Figure 1.5. C8051F314 Block Diagram



### 1.1. CIP-51<sup>™</sup> Microcontroller Core

#### 1.1.1. Fully 8051 Compatible

The C8051F31x family utilizes Silicon Laboratories' proprietary CIP-51 microcontroller core. The CIP-51 is fully compatible with the MCS-51<sup>™</sup> instruction set; standard 803x/805x assemblers and compilers can be used to develop software. The CIP-51 core offers all the peripherals included with a standard 8052, including four 16-bit counter/timers, a full-duplex UART with extended baud rate configuration, an enhanced SPI port, 1280 bytes of internal RAM, 128 byte Special Function Register (SFR) address space, and 29/25/21 I/O pins.

#### 1.1.2. Improved Throughput

The CIP-51 employs a pipelined architecture that greatly increases its instruction throughput over the standard 8051 architecture. In a standard 8051, all instructions except for MUL and DIV take 12 or 24 system clock cycles to execute with a maximum system clock of 12-to-24 MHz. By contrast, the CIP-51 core executes 70% of its instructions in one or two system clock cycles, with only four instructions taking more than four system clock cycles.

The CIP-51 has a total of 109 instructions. The table below shows the total number of instructions that require each execution time.

Clocks to Execute	1	2	2/3	3	3/4	4	4/5	5	8
Number of Instructions	26	50	5	14	7	3	1	2	1

With the CIP-51's maximum system clock at 25 MHz, it has a peak throughput of 25 MIPS. Figure 1.9 shows a comparison of peak throughputs for various 8-bit microcontroller cores with their maximum system clocks.

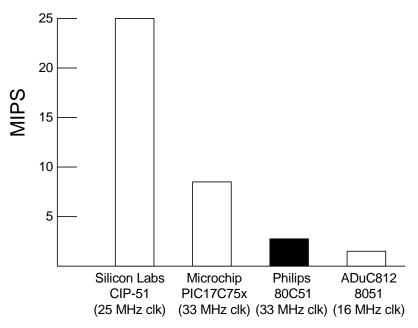


Figure 1.9. Comparison of Peak MCU Execution Speeds



Other electrical characteristics tables are found in the data sheet section corresponding to the associated peripherals. For more information on electrical characteristics for a specific peripheral, refer to the page indicated in Table 3.2.

Peripheral Electrical Characteristics	Page No.
ADC0 Electrical Characteristics	65
External Voltage Reference Circuit Electrical Characteristics	68
Comparator Electrical Characteristics	78
Reset Electrical Characteristics	110
Flash Electrical Characteristics	112
Internal Oscillator Electrical Characteristics	123
Port I/O DC Electrical Characteristics	143

#### Table 3.2. Electrical Characteristics Quick Reference



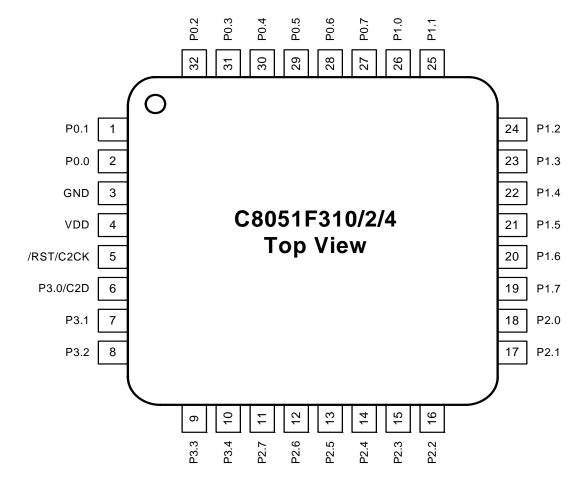
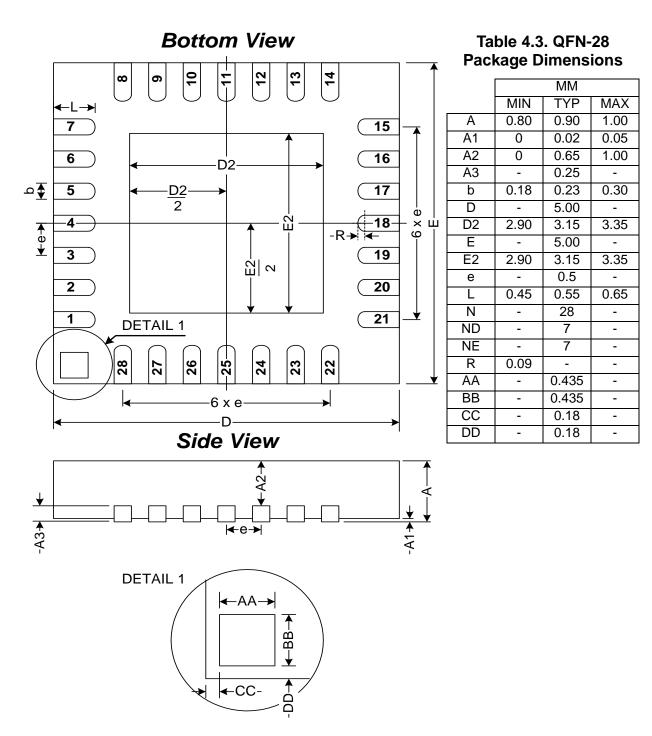


Figure 4.1. LQFP-32 Pinout Diagram (Top View)









#### 5.3.3. Settling Time Requirements

When the ADC0 input configuration is changed (i.e., a different AMUX0 selection is made), a minimum tracking time is required before an accurate conversion can be performed. This tracking time is determined by the AMUX0 resistance, the ADC0 sampling capacitance, any external source resistance, and the accuracy required for the conversion. In low-power tracking mode, three SAR clocks are used for tracking at the start of every conversion. For most applications, these three SAR clocks will meet the minimum tracking time requirements.

Figure 5.5 shows the equivalent ADC0 input circuits for both Differential and Single-ended modes. Notice that the equivalent time constant for both input circuits is the same. The required ADC0 settling time for a given settling accuracy (SA) may be approximated by Equation 5.1. When measuring the Temperature Sensor output or  $V_{DD}$  with respect to GND,  $R_{TOTAL}$  reduces to  $R_{MUX}$ . See Table 5.1 for ADC0 minimum settling time requirements.

### **Equation 5.1. ADC0 Settling Time Requirements**

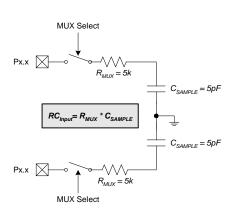
$$t = \ln\left(\frac{2^n}{SA}\right) \times R_{TOTAL} C_{SAMPLE}$$

Where:

SA is the settling accuracy, given as a fraction of an LSB (for example, 0.25 to settle within 1/4 LSB) *t* is the required settling time in seconds

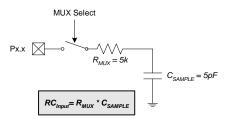
 $R_{TOTAL}$  is the sum of the AMUX0 resistance and any external source resistance.

*n* is the ADC resolution in bits (10).



**Differential Mode** 

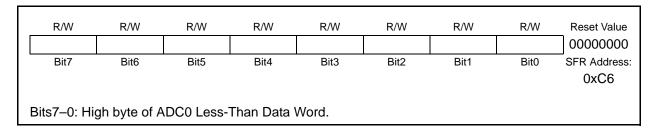




### Figure 5.5. ADC0 Equivalent Input Circuits



### SFR Definition 5.9. ADC0LTH: ADC0 Less-Than Data High Byte



### SFR Definition 5.10. ADC0LTL: ADC0 Less-Than Data Low Byte

	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value	
									0000000	
	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:	
									0xC5	
E	Bits7–0: Low byte of ADC0 Less-Than Data Word.									



The level of Flash security depends on the Flash access method. The three Flash access methods that can be restricted are reads, writes, and erases from the C2 debug interface, user firmware executing on unlocked pages, and user firmware executing on locked pages. Table 10.2 summarizes the Flash security features of the C8051F31x devices.

Action	C2 Debug	User Firmware executing from:			
	Interface	an unlocked page	a locked page		
Read, Write or Erase unlocked pages (except page with Lock Byte)	Permitted	Permitted	Permitted		
Read, Write or Erase locked pages (except page with Lock Byte)	Not Permitted	Flash Error Reset	Permitted		
Read or Write page containing Lock Byte (if no pages are locked)	Permitted	Permitted	Permitted		
Read or Write page containing Lock Byte (if any page is locked)	Not Permitted	Flash Error Reset	Permitted		
Read contents of Lock Byte (if no pages are locked)	Permitted	Permitted	Permitted		
Read contents of Lock Byte (if any page is locked)	Not Permitted	Flash Error Reset	Permitted		
Erase page containing Lock Byte (if no pages are locked)	Permitted	Flash Error Reset	Flash Error Reset		
Erase page containing Lock Byte - Unlock all pages (if any page is locked)	C2 Device Erase Only	Flash Error Reset	Flash Error Reset		
Lock additional pages (change '1's to '0's in the Lock Byte)	Not Permitted	Flash Error Reset	Flash Error Reset		
Unlock individual pages (change '0's to '1's in the Lock Byte)	Not Permitted	Flash Error Reset	Flash Error Reset		
Read, Write or Erase Reserved Area	Not Permitted	Flash Error Reset	Flash Error Reset		

### Table 10.2. Flash Security Summary

C2 Device Erase - Erases all Flash pages including the page containing the Lock Byte.

Flash Error Reset - Not permitted; Causes Flash Error Device Reset (FERROR bit in RSTSRC is '1' after reset).

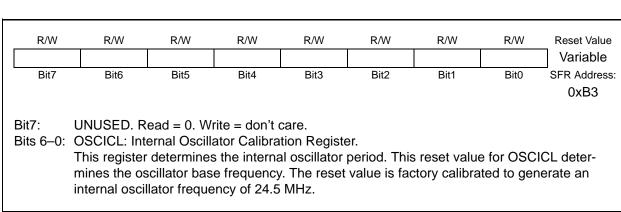
- All prohibited operations that are performed via the C2 interface are ignored (do not cause device reset).

- Locking any Flash page also locks the page containing the Lock Byte.

- Once written to, the Lock Byte cannot be modified except by performing a C2 Device Erase.

- If user code writes to the Lock Byte, the Lock does not take effect until the next device reset.





### SFR Definition 12.1. OSCICL: Internal Oscillator Calibration

### SFR Definition 12.2. OSCICN: Internal Oscillator Control

	R/W R R/W R/W R/W R/W R/W								
IO	SCEN	IFRDY					IFCN1	IFCN0	11000000
	Bit7	it7 Bit6 Bit5 Bit4 Bit3 Bit2 Bit1 Bit0							
									0xB2
	6: 55–2: 51–0:	IOSCEN: Int 0: Internal O 1: Internal O IFRDY: Inter 0: Internal O 1: Internal O UNUSED. R IFCN1-0: Inter 00: SYSCLK 01: SYSCLK 10: SYSCLK 11: SYSCLK	scillator Dis scillator Ena nal Oscillator scillator is r scillator is r ead = 0000 ernal Oscilla derived fro derived fro derived fro	abled. abled. or Frequence ot running unning at p b, Write = c ator Freque m Internal m Internal m Internal	cy Ready Fl at programmed lon't care. ncy Control Oscillator di Oscillator di Oscillator di	Bits. vided by 8. vided by 4. vided by 2.			



SFR	Definition	13.15.	P3: Port3	
••••				

R/W	R/W P3.6	R/W P3.5	R/W P3.4	R/W P3.3	R/W P3.2	R/W P3.1	R/W P3.0	Reset Value				
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:				
Bits7–0:												
	<ul> <li>Bits7–0: P3.[7:0]</li> <li>Write - Output appears on I/O pins.</li> <li>0: Logic Low Output.</li> <li>1: Logic High Output (high impedance if corresponding P3MDOUT.n bit = 0).</li> <li>Read - Always reads '1' if selected as analog input in register P3MDIN. Directly reads Port pin when configured as digital input.</li> <li>0: P3.n pin is logic low.</li> <li>1: P3.n pin is logic high.</li> </ul>											
Note:	Only P3.0–P3 Port pin on C8			•	051F310/2/4	devices; On	ly P3.0 is ass	ociated with a				

### SFR Definition 13.16. P3MDIN: Port3 Input Mode

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value			
-	-	-						11111111			
Bit7	Bit6 Bit5 Bit4 Bit3 Bit2 Bit1 Bit0 SFR Addres 0xF4										
Note:	Only P3.0–P3 Port pin on C8				3051F310/2/4	devices; Or	nly P3.0 is a	ssociated with			



### SFR Definition 13.17. P3MDOUT: Port3 Output Mode

R	2/W -	R/W -	R/W -	R/W	R/W	R/W	R/W	R/W	Reset Value 00000000							
E	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	Bit0 SFR Address: 0xA7							
Bits7 Bits4	.–0: ( t	JNUSED. R Output Confi er P3MDIN 0: Correspor 1: Correspor	guration Bi is logic 0. nding P3.n (	ts for P3.4– Output is op	P3.0 (respe ben-drain.	ectively): igr	nored if corr	esponding	bit in regis-							
Note:		Only P3.0–P3.4 are associated with Port pins on C8051F310/2/4 devices; Only P3.0 is associated with a Port pin on C8051F311/3/5/6/7 devices.														

### Table 13.1. Port I/O DC Electrical Characteristics

 $V_{DD}$  = 2.7 to 3.6 V, -40 to +85 °C unless otherwise specified

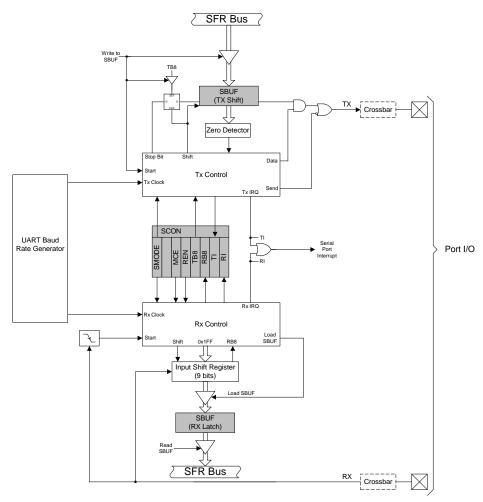
Parameters	Conditions	Min	Тур	Max	Units
	I <sub>OH</sub> = −3 mA, Port I/O push-pull	V <sub>DD</sub> – 0.7	—		
Output High Voltage	$I_{OH} = -10 \ \mu A$ , Port I/O push-pull	V <sub>DD</sub> – 0.1	—	—	V
	I <sub>OH</sub> = –10 mA, Port I/O push-pull	—	$V_{DD} - 0.8$	—	
	I <sub>OL</sub> = 8.5 mA		—	0.6	
Output Low Voltage	I <sub>OL</sub> = 10 μA	—	—	0.1	V
	I <sub>OL</sub> = 25 mA	—	1.0	_	
Input High Voltage		2.0	—	_	V
Input Low Voltage			—	0.8	V
	Weak Pullup Off		—	±1	
Input Leakage Current	Weak Pullup On, V <sub>IN</sub> = 0 V	—	25	40	μA

### 15. UART0

UART0 is an asynchronous, full duplex serial port offering modes 1 and 3 of the standard 8051 UART. Enhanced baud rate support allows a wide range of clock sources to generate standard baud rates (details in **Section "15.1. Enhanced Baud Rate Generation" on page 164**). Received data buffering allows UART0 to start reception of a second incoming data byte before software has finished reading the previous data byte.

UART0 has two associated SFRs: Serial Control Register 0 (SCON0) and Serial Data Buffer 0 (SBUF0). The single SBUF0 location provides access to both transmit and receive registers. Writes to SBUF0 always access the Transmit register. Reads of SBUF0 always access the buffered Receive register; it is not possible to read data from the Transmit register.

With UART0 interrupts enabled, an interrupt is generated each time a transmit is completed (TI0 is set in SCON0), or a data byte has been received (RI0 is set in SCON0). The UART0 interrupt flags are not cleared by hardware when the CPU vectors to the interrupt service routine. They must be cleared manually by software, allowing software to determine the cause of the UART0 interrupt (transmit complete or receive complete).







	Frequency: 11.0592 MHz						
	Target Baud Rate (bps)	Baud Rate % Error	Oscilla- tor Divide Factor	Timer Clock Source	SCA1-SCA0 (pre-scale select)*	T1M*	Timer 1 Reload Value (hex)
	230400	0.00%	48	SYSCLK	XX	1	0xE8
	115200	0.00%	96	SYSCLK	XX	1	0xD0
	57600	0.00%	192	SYSCLK	XX	1	0xA0
from Osc.	28800	0.00%	384	SYSCLK	XX	1	0x40
$\sim$	14400	0.00%	768	SYSCLK / 12	00	0	0xE0
SYSCLK External	9600	0.00%	1152	SYSCLK / 12	00	0	0xD0
	2400	0.00%	4608	SYSCLK / 12	00	0	0x40
	1200	0.00%	9216	SYSCLK / 48	10	0	0xA0
	230400	0.00%	48	EXTCLK / 8	11	0	0xFD
SYSCLK from Internal Osc.	115200	0.00%	96	EXTCLK / 8	11	0	0xFA
	57600	0.00%	192	EXTCLK / 8	11	0	0xF4
	28800	0.00%	384	EXTCLK / 8	11	0	0xE8
	14400	0.00%	768	EXTCLK / 8	11	0	0xD0
	9600	0.00%	1152	EXTCLK / 8	11	0	0xB8

# Table 15.5. Timer Settings for Standard Baud RatesUsing an External 11.0592 MHz Oscillator

X = Don't care

\*Note: SCA1–SCA0 and T1M bit definitions can be found in Section 17.1.

Table 15.6. Timer Settings for Standard Baud Rates
Using an External 3.6864 MHz Oscillator

	Frequency: 3.6864 MHz						
	Target Baud Rate (bps)	Baud Rate% Error	Oscilla- tor Divide Factor	Timer Clock Source	SCA1-SCA0 (pre-scale select)*	T1M*	Timer 1 Reload Value (hex)
	230400	0.00%	16	SYSCLK	XX	1	0xF8
	115200	0.00%	32	SYSCLK	XX	1	0xF0
	57600	0.00%	64	SYSCLK	XX	1	0xE0
from Osc.	28800	0.00%	128	SYSCLK	XX	1	0xC0
	14400	0.00%	256	SYSCLK	XX	1	0x80
SYSCLK External (	9600	0.00%	384	SYSCLK	XX	1	0x40
	2400	0.00%	1536	SYSCLK / 12	00	0	0xC0
	1200	0.00%	3072	SYSCLK / 12	00	0	0x80
SYSCLK from Internal Osc.	230400	0.00%	16	EXTCLK/8	11	0	0xFF
	115200	0.00%	32	EXTCLK / 8	11	0	0xFE
	57600	0.00%	64	EXTCLK / 8	11	0	0xFC
	28800	0.00%	128	EXTCLK / 8	11	0	0xF8
	14400	0.00%	256	EXTCLK / 8	11	0	0xF0
	9600	0.00%	384	EXTCLK / 8	11	0	0xE8

X = Don't care

\*Note: SCA1–SCA0 and T1M bit definitions can be found in **Section 17.1**.



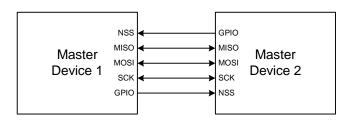


Figure 16.2. Multiple-Master Mode Connection Diagram

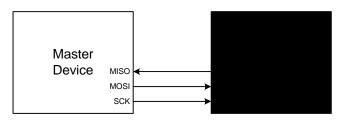


Figure 16.3. 3-Wire Single Master and Slave Mode Connection Diagram

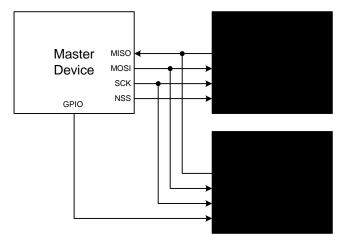


Figure 16.4. 4-Wire Single Master and Slave Mode Connection Diagram



#### 17.1.2. Mode 1: 16-bit Counter/Timer

Mode 1 operation is the same as Mode 0, except that the counter/timer registers use all 16 bits. The counter/timers are enabled and configured in Mode 1 in the same manner as for Mode 0.

#### 17.1.3. Mode 2: 8-bit Counter/Timer with Auto-Reload

Mode 2 configures Timer 0 and Timer 1 to operate as 8-bit counter/timers with automatic reload of the start value. TL0 holds the count and TH0 holds the reload value. When the counter in TL0 overflows from all ones to 0x00, the timer overflow flag TF0 (TCON.5) is set and the counter in TL0 is reloaded from TH0. If Timer 0 interrupts are enabled, an interrupt will occur when the TF0 flag is set. The reload value in TH0 is not changed. TL0 must be initialized to the desired value before enabling the timer for the first count to be correct. When in Mode 2, Timer 1 operates identically to Timer 0.

Both counter/timers are enabled and configured in Mode 2 in the same manner as Mode 0. Setting the TR0 bit (TCON.4) enables the timer when either GATE0 (TMOD.3) is logic 0 or when the input signal /INT0 is active as defined by bit IN0PL in register IT01CF (see **Section "8.3.2. External Interrupts" on page 95** for details on the external input signals /INT0 and /INT1).

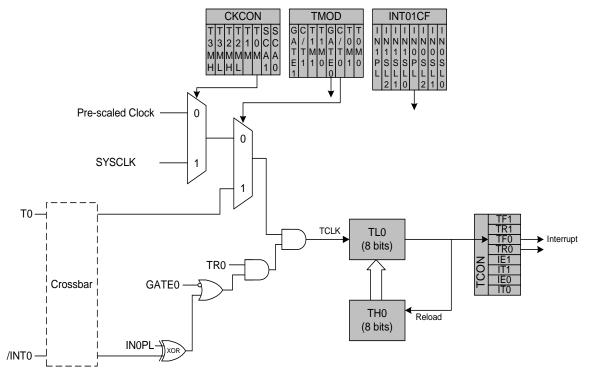


Figure 17.2. T0 Mode 2 Block Diagram



#### 18.2.2. Software Timer (Compare) Mode

In Software Timer mode, the PCA counter/timer value is compared to the module's 16-bit capture/compare register (PCA0CPHn and PCA0CPLn). When a match occurs, the Capture/Compare Flag (CCFn) in PCA0CN is set to logic 1 and an interrupt request is generated if CCF interrupts are enabled. The CCFn bit is not automatically cleared by hardware when the CPU vectors to the interrupt service routine, and must be cleared by software. Setting the ECOMn and MATn bits in the PCA0CPMn register enables Software Timer mode.

**Important Note About Capture/Compare Registers**: When writing a 16-bit value to the PCA0 Capture/ Compare registers, the low byte should always be written first. Writing to PCA0CPLn clears the ECOMn bit to '0'; writing to PCA0CPHn sets ECOMn to '1'.

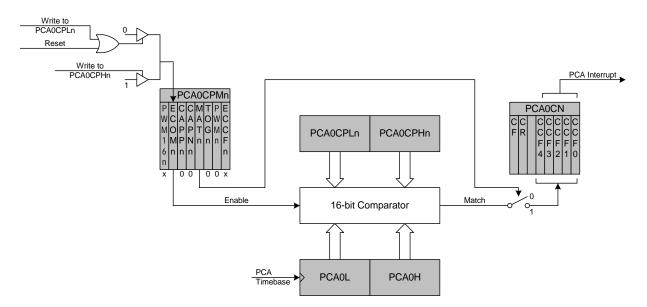


Figure 18.5. PCA Software Timer Mode Diagram



### **19. Revision Specific Behavior**

This chapter contains behavioral differences between C8051F310/1 "REV A" and "REV B" or later devices. These differences do not affect the functionality or performance of most systems and are described below.

#### **19.1.** Revision Identification

The Lot ID Code on the top side of the device package can be used for decoding device revision information. On C8051F310 devices, the revision letter is the second-to-last letter of the Lot ID Code. On C8051F311 devices, the revision letter is the last letter of the Lot ID Code. Figure 19.1 shows how to find the Lot ID Code on the top side of the device package.

```
C8051F310 Package Marking
C8051F310
T2ABGFAC
^ indicates REV A
0227 EP
```

C8051F311 Package Marking		
CYG		
F311		
ABGF <b>A</b>	indicates REV A	

### Figure 19.1. Reading Package Marking

#### 19.2. Reset Behavior

The reset behavior of C8051F310/1 "REV A" devices is different than "REV B" and later devices. The differences affect the state of the RST pin during a V<sub>DD</sub> Monitor reset and GPIO pins during any device reset.

#### 19.2.1. Weak Pullups on GPIO Pins

On "REV A" devices, GPIO pins are tri-stated with weak pullups **disabled** during the assertion phase of any reset. The pullups are enabled immediately following reset de-assertion.

On "REV B" and later devices, GPIO pins are tri-stated with weak pullups **enabled** during and after the assertion phase of any reset.

#### 19.2.2. $V_{DD}$ Monitor and the RST Pin

On "REV A" devices, a  $V_{DD}$  Monitor reset does not affect the state of the  $\overline{RST}$  pin.

On "REV B" and later devices, a  $V_{DD}$  Monitor reset will pull the  $\overline{RST}$  pin low for the duration of the brownout condition.

